



NOTES: 010111
BOX AF

AMENDMENT UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
GROUP 1765
PATENT APPLICATION

AF/1765
#10/C
Hedde
7/12/02
(12)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q61045

Fumiyoshi ONO

Appln. No.: 09/672,776

Group Art Unit: 1765

Confirmation No.: 2256

Examiner: Charlotte A. Brown

Filed: September 29, 2000

For: COMPOSITION FOR POLISHING METAL ON SEMICONDUCTOR WAFER AND
METHOD OF USING SAME

RECEIVED
JUL 8 2002
TC 1700

AMENDMENT UNDER 37 C.F.R. § 1.116

ATTN: BOX AF
Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated July 3, 2002, review and reconsideration on the merits are respectfully requested in view of the following amendments and remarks.

Please amend the above-identified application as follows:

IN THE CLAIMS:

Please enter the following amended claims:

6. (amended) A method for polishing a metal film on a semiconductor substrate, comprising the steps of:
providing a semiconductor substrate comprising a metal film and an insulating film therein;

BEST AVAILABLE COPY